

## Claims

- [c1] 1. A semiconductor device comprising:
  - a substrate;
  - a first semiconductor chip mounted on the substrate;
  - and
  - a second semiconductor chip mounted on the first semiconductor chip, and being smaller in size and thickness than the first semiconductor chip.
- [c2] 2. The semiconductor device of claim 1, wherein an edge of a lower surface of the second semiconductor chip confronting an upper surface of the first semiconductor chip is chamfered.
- [c3] 3. The semiconductor device of claim 1 wherein the second semiconductor chip is mounted on the first semiconductor chip other than in the center of the first semiconductor chip.
- [c4] 4. The semiconductor device of claim 3 wherein the size of the first semiconductor chip is at least twice the size of the second semiconductor chip.
- [c5] 5. A semiconductor device comprising:
  - a substrate;

a first semiconductor chip mounted on the substrate;  
and

a second semiconductor chip, mounted on the first  
semiconductor chip, being smaller in size than the  
first semiconductor chip, and having an edge of a  
lower surface of the second semiconductor chip con-  
fronting an upper surface of the first semiconductor  
chip that is chamfered.

[c6] 6. The semiconductor device of claim 5 wherein the sec-  
ond semiconductor chip is mounted on the first semi-  
conductor chip closer to an end thereof than at the cen-  
ter thereof.

[c7] 7. The semiconductor device of claim 6 wherein the size  
of the first semiconductor chip is at least twice the size  
of the second semiconductor chip.